TI's 2019 APEC
Conference Participation

POWER
DESIGN CHALLENGES – SOLVED.

Texas Instruments

Title	Session/Paper No.	Presenter/Author
Technical session - Poster **Check here for updated times and rooms**		
6.6 kW three-phase interleaved Totem Pole PFC design with 98.9% peak efficiency for HEV/EV onboard charger	D01 Paper No. 1136	Xun Gong
Thermal monitoring technique for limiting energy accumulation in automotive power switches within SOA	D17 Paper No. 1876	Eung Jung Kim, Sualp Aras, Kyle Schulmeyer, Abidur Rahman
Parasitic parameter effects on the dv/dt-induced low-side MOSFET false turn-on in synchronous buck converters	D03 Paper No. 1428	Manjing Xie
Industry session **Check here for updated times and rooms**		
5 common mistakes in point-of-load DC-DC converters and how to avoid them	IS02 Paper No. 1037	Pradeep Shenoy, Anthony Fagnani
Advanced active clamp flyback control for high-density AC/DC adapters	IS07 Paper No. 1058	Bing Lu
USB type-C AND power delivery ≤ 100 W	IS07 Paper No. 1091	Deric Waters, Indumini Ranmuthu
Optimizing light load efficiency in TM boost PFCs	IS02 Paper No. 1094	Billy Long, Joseph Leisten
Update on GaN and SiC activities within JEDEC JC-70 committee	209AB Paper No. 1100	Stephanie Butler
Technical session - Lecture **Check here for updated times and rooms**		
Small signal analysis of active clamp flyback converters in transition mode and burst mode	T04 Paper No.1616	Pei-Hsin Liu
Exhibitor session **Check here for updated times and rooms**		
Isolated gate drivers – how do I know which ones right for my application?	Exhibitor session	Nagarajan Sridhar
RAP session **Check here for updated times and rooms**		
Power supply on chip (Pwr SOC) vs. power supply in package (Pwr SIP) vs discrete. What is the future?	RAP session 2	Indumini Ranmuthu (moderator), Sreenivasan Koduri
Is magnetics really the constraint or are magnetics waiting for everything else to catch up?	RAP session 3	Steve Tom

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